

Materials Declaration Form

IPC	1752	Version	2			
Form Type *	Distribute	version	2			
Sectionals *	Material Info	Subsectionals *	A-D			
	Manufacturing Info		* : Required Field			

Supplier Information								
Company Name *	STMicroelectronics	Response Date *	2016-05-10					
Contact Name *	Refer to " Supplier Comment" section	er to " Supplier Comment" section Contact Title Refer to " Supplier Comment" section						
Contact Phone *	Refer to " Supplier Comment" section	Refer to " Supplier Comment" section						
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD Champion					
	efer to " Supplier Comment" section Representative Email * Refer to " Supplier Comment" section							
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section					

Uncertainty Statement

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Legal Statement

Supplier Acceptance * true Legal Declaration * Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product								
Mfr Item Number	Mfr Item Name Version		Mfr Site	Date				
	MZAI*UAD6BBA	А	SH1A	2016-05-10				
	Amount	UoM	Unit type	ST ECOPACK Grade				
	0.53	mg	Each	ECOPACK® 2				

Manufacturing information								
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles						
NAC	NAC	NAC						
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	life.augmented				
Tin/Silver/Copper (SAC405)	Tin/Silver/Copper (Sn/Ag/Cu)	NAC		meraagmemea				

Package Designator	Size	Nbr of instances	Shape	
WAFER	0.72 - 0.72 - 0.4	4	NAC	
Comment	Package: A0FJ FLIPCHIP PITCH400 4BP	DIA 160UM; MDF valid for LD39130SJ3	33R	

QueryList: ROHS directive 2011/65/EU _ July 2011							
Query							
Product(s) meets EU RoHS requirement w	thout any exemptions	true					
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)							
Product(s) meets EU RoHS requirements b	Product(s) meets EU RoHS requirements by application of the selected exemption(s)						
Product(s) does not meet EU RoHS requirements and is not under exemptions							
Product(s) is obsolete, no information is available							
Product(s) is unknown, no information is available							
Exemption Id. Description							

QueryList: REACH-17th December 2015									
Query Response									
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH									
CategoryLevel_Name CategoryLevel_Threshold amount in product (mg) Application									

Material Composition Declaration		Mfr Item Name	MZAI*U	AD6BBA								
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.526	mg	supplier	die	Silicon (Si)	7440-21-3		0.483	mg	918251	918251
Die				supplier	metallization	Aluminium (AI)	7429-90-5		0.003	mg	5703	5703
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	1901	1901
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.001	mg	1901	1901
Die				supplier	UBM	Copper (Cu)	7440-50-8		0.003	mg	5703	5703
Die				supplier	UBM	Nickel (Ni)	7440-02-0		0.003	mg	5703	5703
Die				supplier	bump	Tin (Sn)	7440-31-5		0.031	mg	58935	58935
Die				supplier	bump	Silver (Ag)	7440-22-4		0.001	mg	1901	1901